

In the Claim:

1. (Currently Amended) A method of detecting a polishing end point in a chemical mechanical polishing process, comprising the steps of:

using a sensor detecting to detect a variation in the concentration of a material within an initial polishing layer or to detect a variation in the concentration of a material within a polishing stop layer, which are by measuring the concentration of the material within the initial polishing layer or the concentration of the material within the polishing stop layer contained in polishing wastewater drained during a polishing process;

using an EDPend point detection system to database information detected by the sensor;

feeding back the a result to a polisher in real time, wherein if a result that there is no change in the concentration of the material within the initial polishing layer is obtained, the result is the polishing process continuously proceeds with an initial polishing process condition;

if a result that variation in the concentration of the material within the initial polishing layer is reduced and variation in the concentration of the material within the polishing stop layer is increased, is obtained, the result is performing the polishing process by lowering a under a reduced polishing pressure; and

if a result that variation in the concentration of the material within the initial polishing layer is not reduced but kept constant and variation in the concentration of the material within the polishing stop layer is not increased but kept constant, is obtained, the result is using the EDPend point detection system to send a polishing process stop signal to the polisher, thus stopping the polishing process.